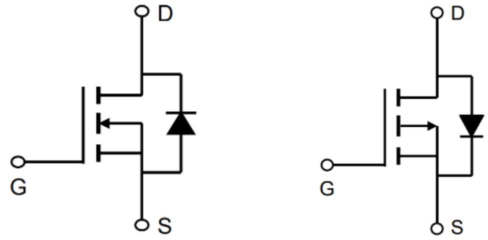
AP15G04NF

40V N+P-Channel Enhancement Mode MOSFET

Description

The AP15G04NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



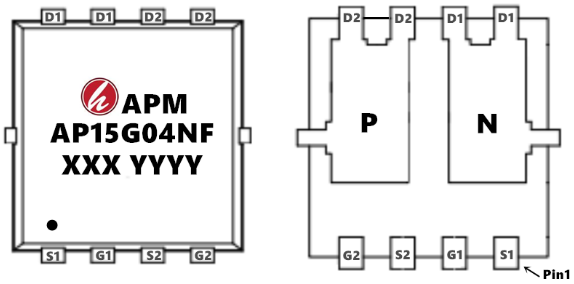
General Features

V_{DS} = 40V I_D =21A

$R_{DS(ON)}$ < 17mΩ @ V_{GS}=10V

V_{DS} = -40V I_D =-18A

$R_{DS(ON)}$ < 45mΩ @ V_{GS}=-10V

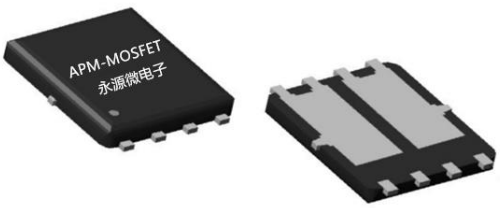


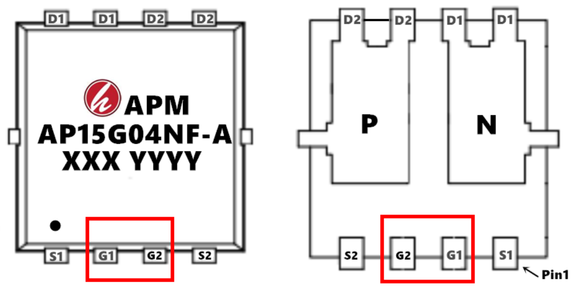
Application

Wireless charging

Boost driver

Brushless motor





Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP15G04NF	PDFN5*6-8L	AP15G04NF XXX YYYY	5000
AP15G04NF-A	PDFN5*6-8L	AP15G04NF-A XXX YYYY	5000

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	N-Ch	P-Ch	Units
V_{DS}	Drain-Source Voltage	40	-40	V
V_{GS}	Gate-Source Voltage	±20	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	21	-18	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	17.5	-14	A
I_{DM}	Pulsed Drain Current[2]	38	-32	A
EAS	Single Pulse Avalanche Energy[3]	66	66	mJ
I_{AS}	Avalanche Current	28.8	-23.2	A
P_D@T_C=25℃	Total Power Dissipation[4]	25	31.3	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	℃
$R_{θJA}$	Thermal Resistance Junction-Ambient [1]	62		℃/W
$R_{θJC}$	Thermal Resistance Junction-Case[1]	5		℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	40	46	---	V
△BV_{DSS}/△T_J	BVDSS Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.032	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=15A	---	13.5	17	mΩ
		V_{GS}=4.5V , I_D=10A	---	18.4	24	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.6	2.5	V
△$V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.8	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=32V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=15A	---	34	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	2.1	---	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=32V , V_{GS}=4.5V , I_D=15A	---	10	---	nC
Q_{gs}	Gate-Source Charge		---	2.55	---	
Q_{gd}	Gate-Drain Charge		---	4.8	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=20V , V_{GS}=10V , R_G=3.3Ω I_D=15A	---	2.8	---	ns
T_r	Rise Time		---	12.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	21.2	---	
T_f	Fall Time		---	6.4	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	1013	---	pF
C_{oss}	Output Capacitance		---	107	---	
C_{rss}	Reverse Transfer Capacitance		---	76	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	40	A
I_{SM}	Pulsed Source Current[2,5]		---	---	85	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.2	V
t_{rr}	Reverse Recovery Time	I_F=15A , dI/dt=100A/μs , T_J=25℃	---	10	---	nS
Q_{rr}	Reverse Recovery Charge		---	3.1	---	nC

Note :

1、The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2、The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3、The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=10A
4、The power dissipation is limited by 150℃ junction temperature
5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Electrical Characteristics (T_C=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-40	-46	---	V
△BV_{DSS}/△T_J	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=-1mA	---	-0.012	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=-10V , I_D=-15A	---	35	45	mΩ
		V_{GS}=-4.5V , I_D=-4A	---	48	60	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =-250uA	-1.2	-1.6	-2.5	V
△$V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4.32	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-32V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=-32V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=-5V , I_D=-8A	---	12.6	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	13	16	Ω
Q_g	Total Gate Charge (-4.5V)	V_{DS}=-20V , V_{GS}=-4.5V , I_D=-12A	---	9	---	nC
Q_{gs}	Gate-Source Charge		---	2.54	---	
Q_{gd}	Gate-Drain Charge		---	3.1	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=-15V, V_{GS}=-10V , R_G=3.3Ω, I_D=-1A	---	19.2	---	ns
T_r	Rise Time		---	12.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	48.6	---	
T_f	Fall Time		---	4.6	---	
C_{iss}	Input Capacitance	V_{DS}=-15V , V_{GS}=0V , f=1MHz	---	1004	---	pF
C_{oss}	Output Capacitance		---	108	---	
C_{rss}	Reverse Transfer Capacitance		---	80	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current			-20	A
I_{SM}	Pulsed Source Current[2,5]				-40	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=-1A , T_J=25℃			-1	V

Note :

1、The data tested by surface mo unted on a 1 $inch^2$ FR-4 board with 2OZ copper.
2、The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3、The EAS data shows Max. rating . The test condition is V^{DD}=-25V,V^{GS}=-10V,L=0.1mH,I^{AS}=-10A
4、The power dissipation is limited by 150℃ junction temperature
5 、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

40V N+P-Channel Enhancement Mode MOSFET

N-Typical Characteristics

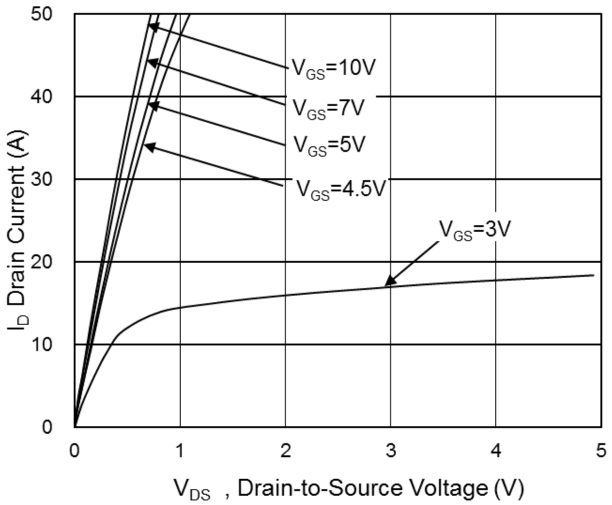


Fig.1 Typical Output Characteristics

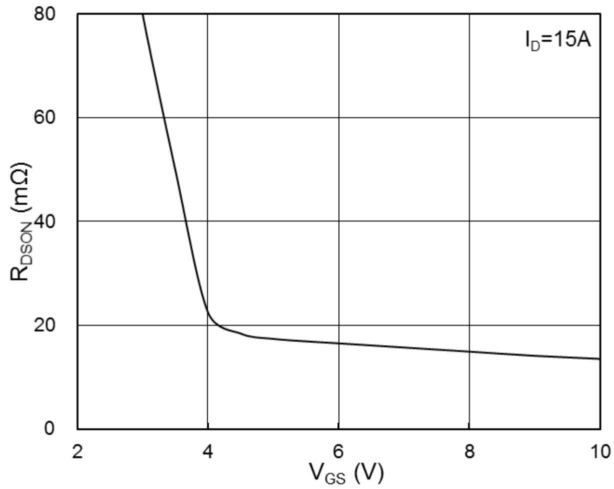


Fig.2 On-Resistance vs. G-S Voltage

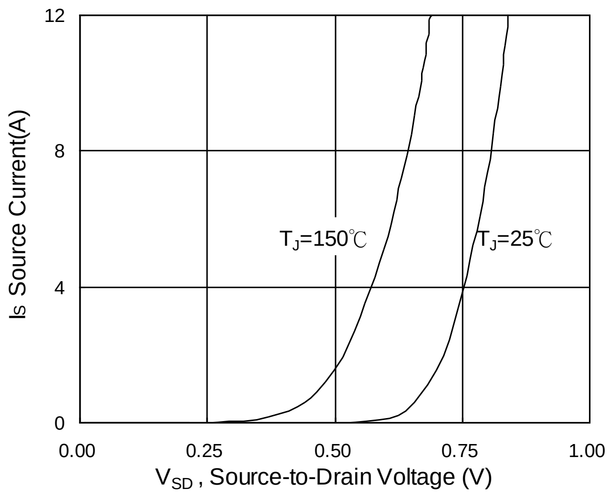


Fig.3 Forward Characteristics of Reverse

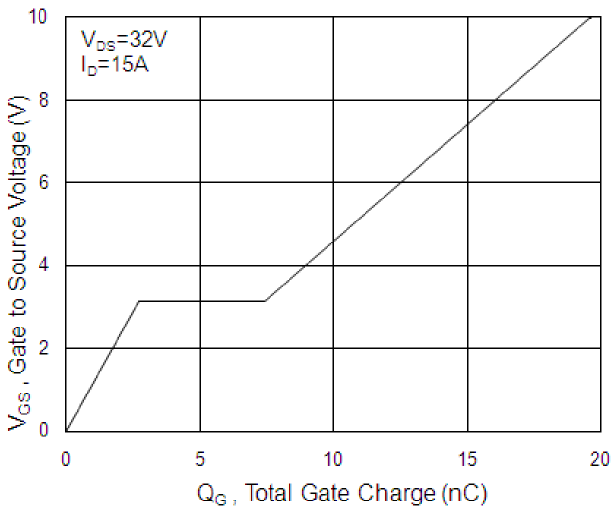


Fig.4 Gate-Charge Characteristics

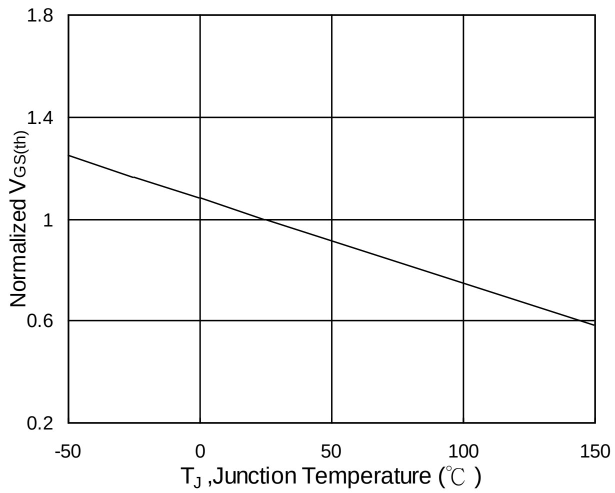


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

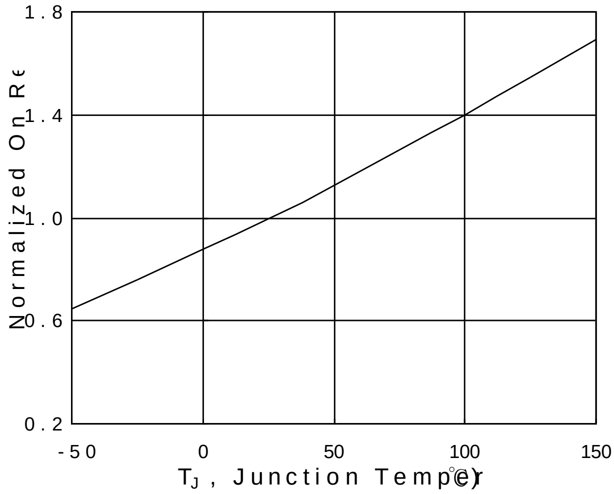


Fig.6 Normalized R_{DSON} vs. T_J

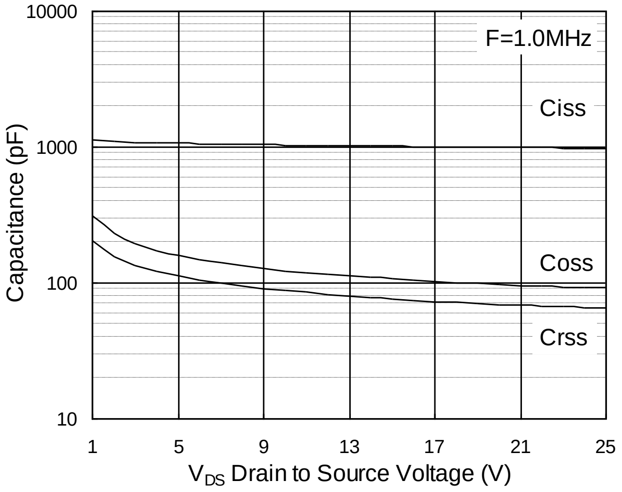


Fig.7 Capacitance

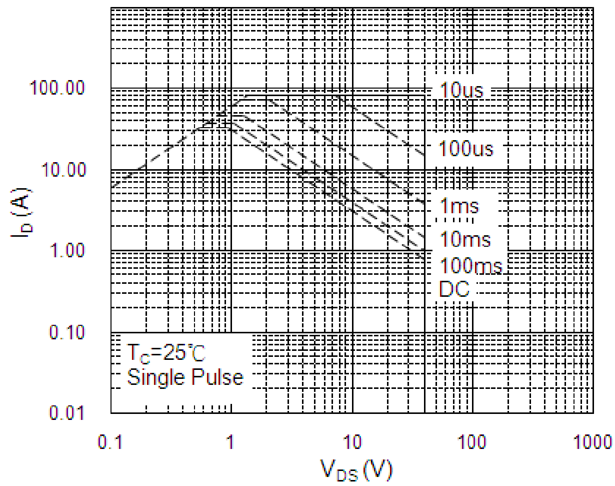


Fig.8 Safe Operating Area

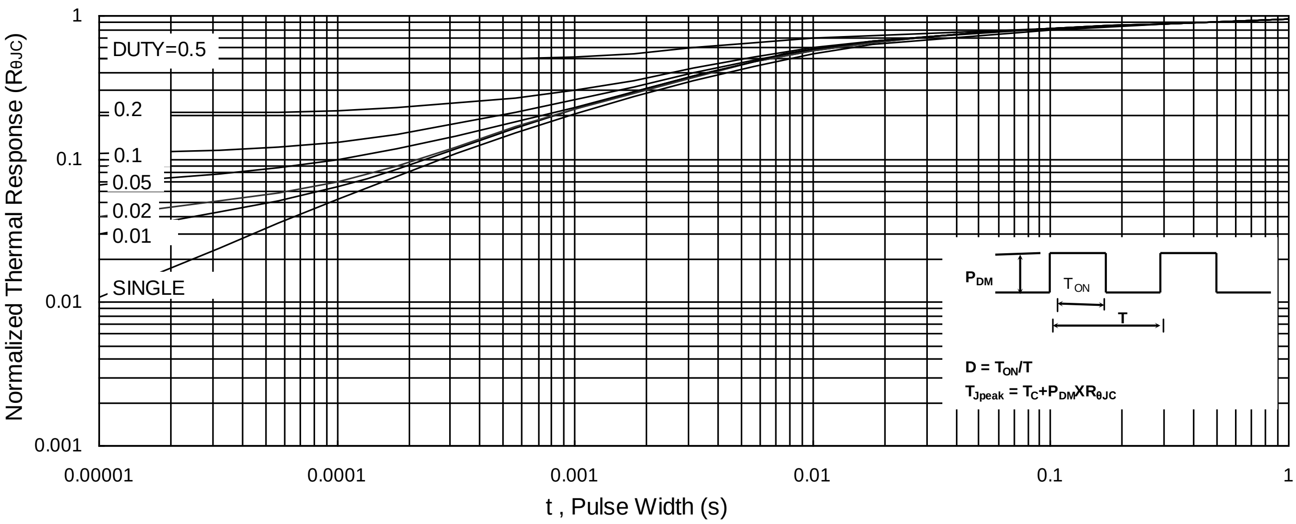


Fig.9 Normalized Maximum Transient Thermal Impedance

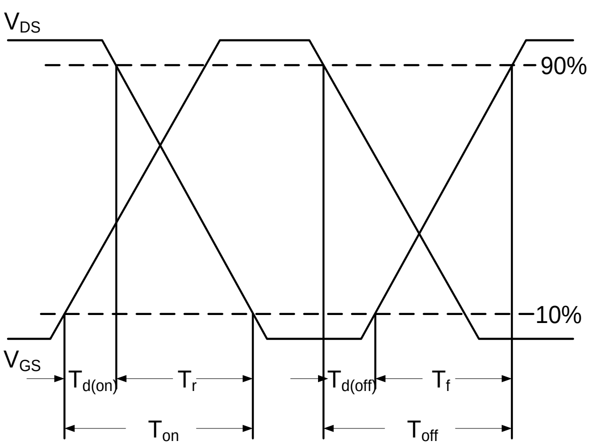


Fig.10 Switching Time Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

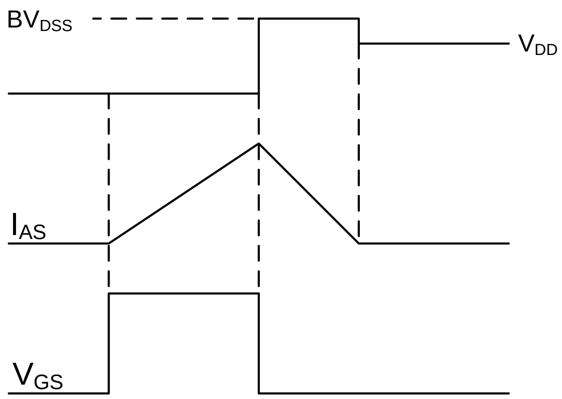


Fig.11 Unclamped Inductive Switching Waveform

P-Typical Characteristics

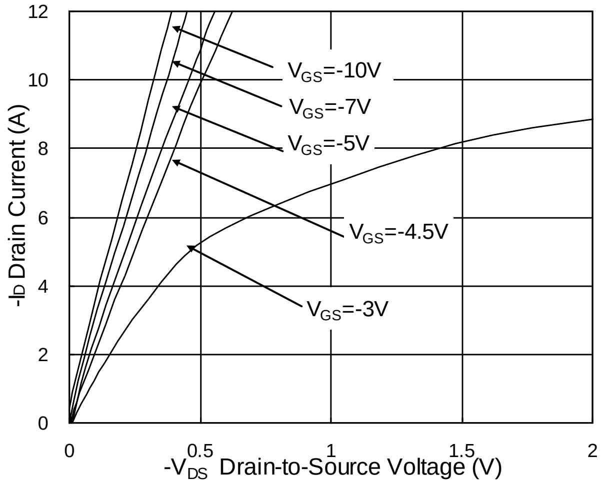


Fig.1 Typical Output Characteristics

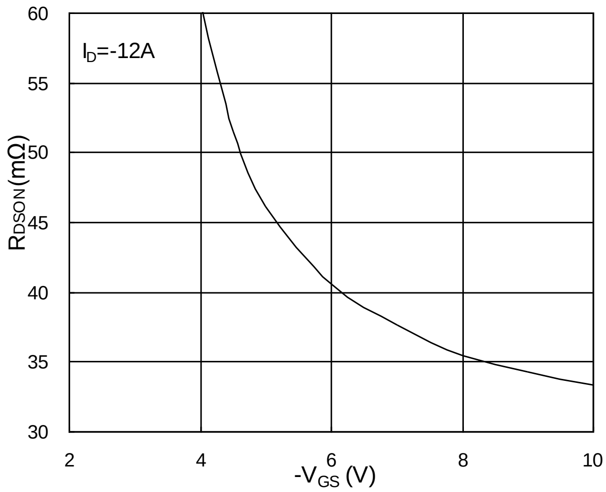


Fig.2 On-Resistance v.s Gate-Source

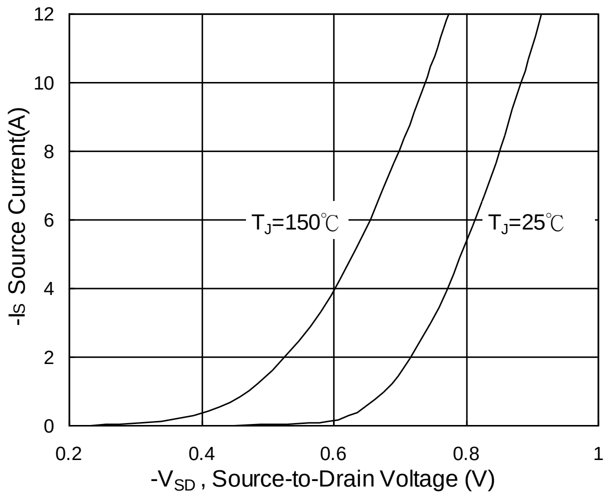


Fig.3 Forward Characteristics of Reverse

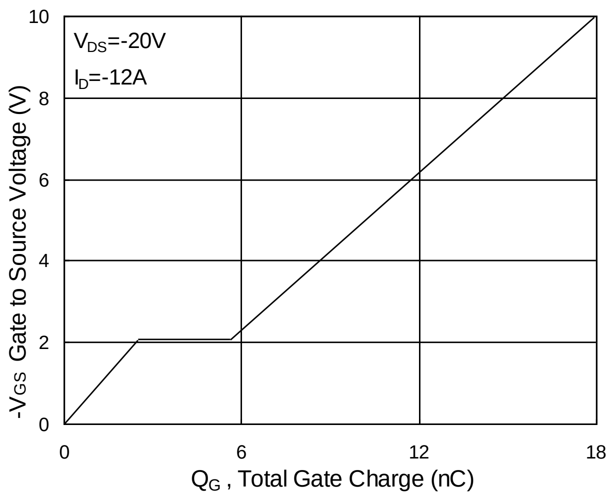


Fig.4 Gate-Charge Characteristics

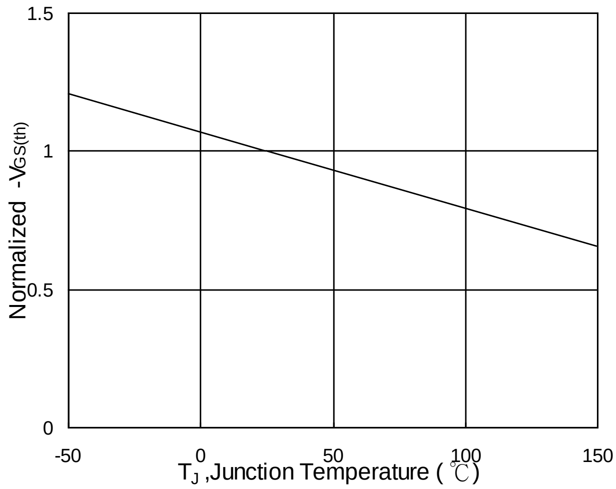


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

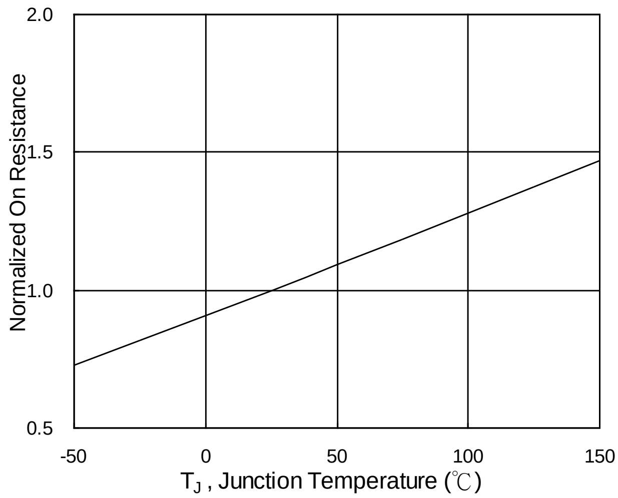


Fig.6 Normalized R_{DSON} v.s T_J

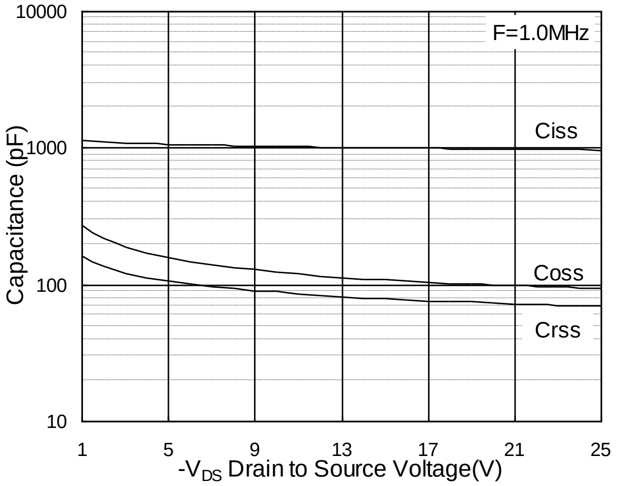


Fig.7 Capacitance

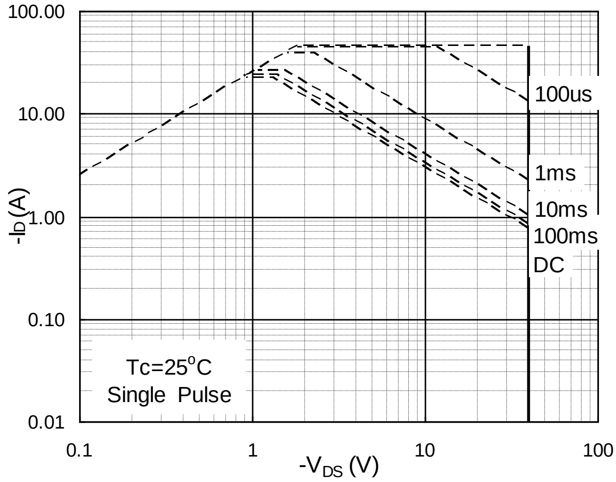


Fig.8 Safe Operating Area

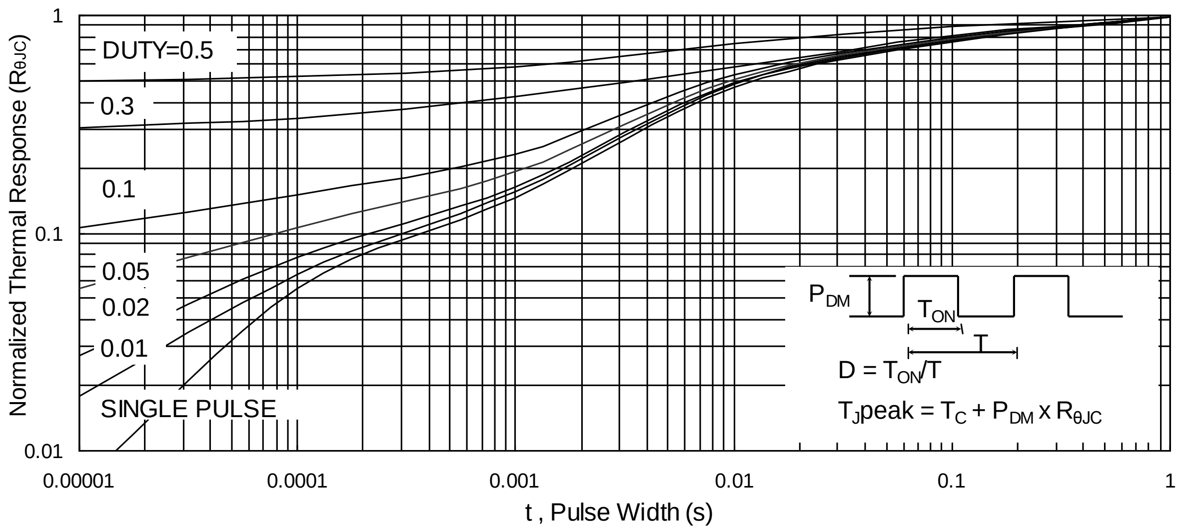


Fig.9 Normalized Maximum Transient Thermal Impedance

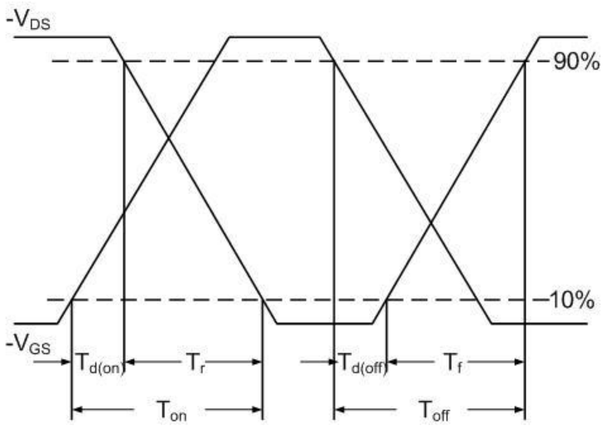


Fig.10 Switching Time Waveform

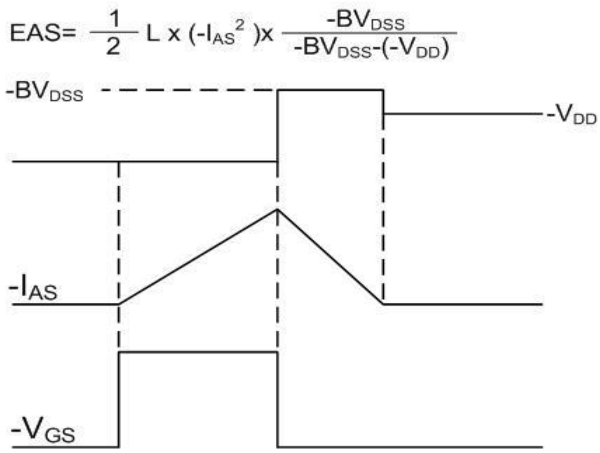
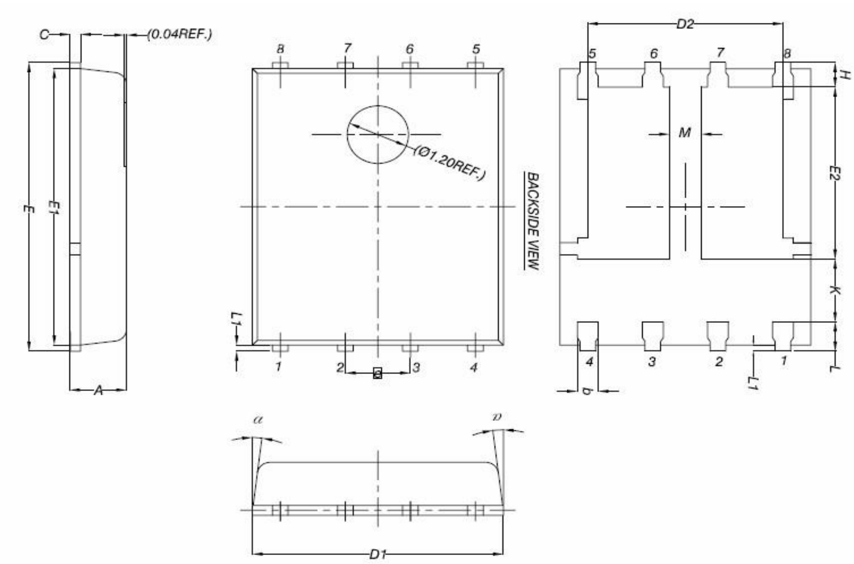


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-DFN5*6-8L-JQ Double



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.66	5.76	5.83
E2	3.37	3.47	3.58
e	1.27BSC		
H	0.41	0.51	0.61
K	1.10	--	--
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	--	--
a	0°	--	12°

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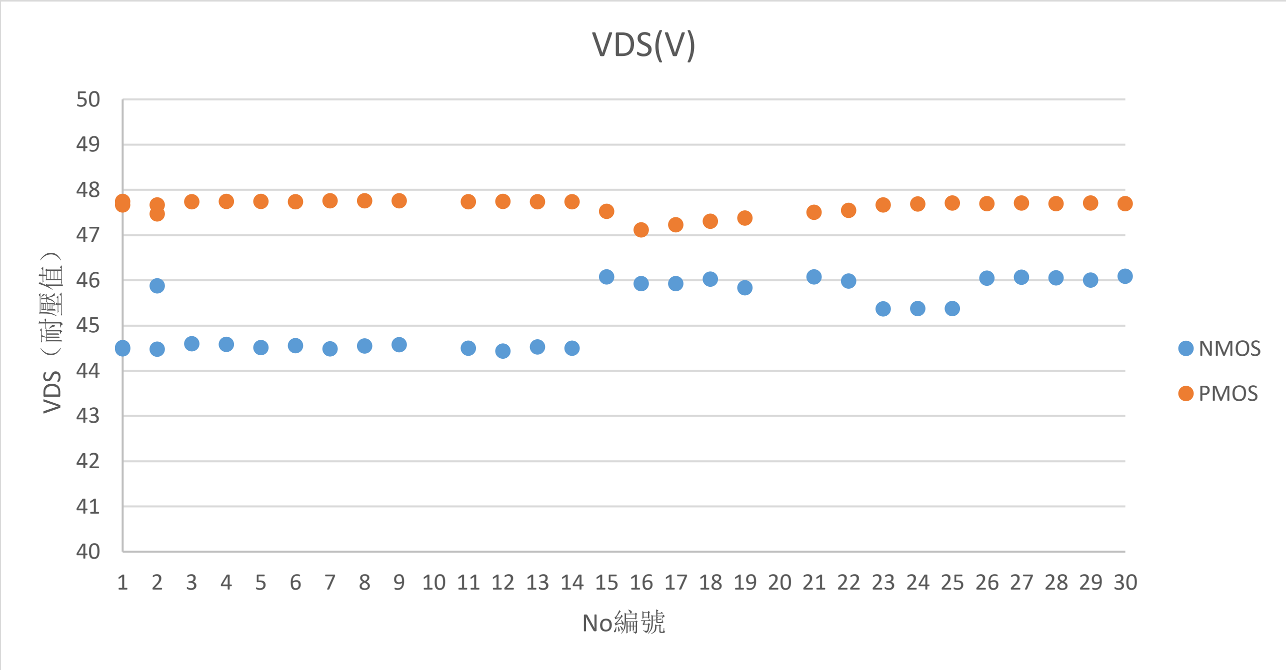
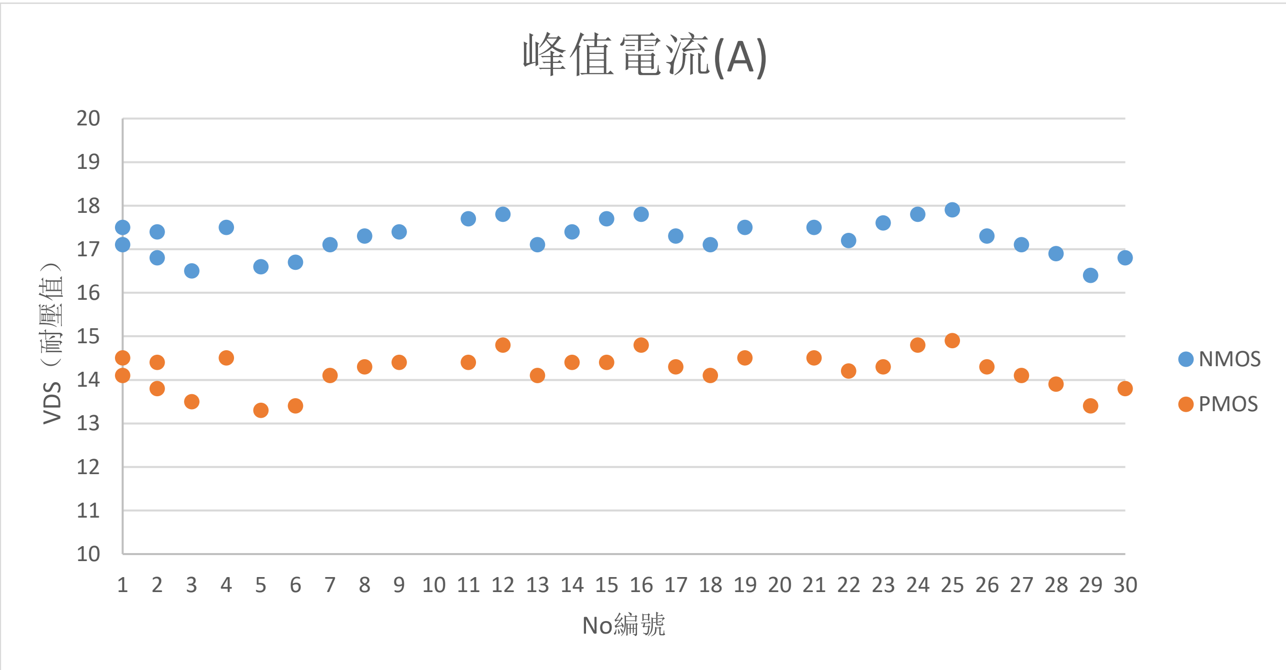
Edition	Date	Change
Rve1.0	2020/2/30	Initial release

Test Report For 30PCS（30pcs 典型測試報告）

Simulation 24V Brushless motor





測試條件：工作電壓：25V　驅動電壓：10V